

# SKB360I Bluetooth 4.0 Low Energy Module Datasheet

Name: Bluetooth 4.0 Low Energy Module

Model No.: SKB360I

Version: V1.01

Revision History:

Revision	Description	Approved	Date
V1.01	Initial Release	Hogan	20160611

## Product Description

The SKB360I is a highly integrated Bluetooth 4.0 BLE module, designed for high data rate, short-range wireless communication in the 2.4GHz ISM band. The module is designed base on Nordic nRF51822 radio Transceiver IC, has a 32 bit ARM Cortex-M0 CPU, flash memory and analog and digital peripherals. The SKB360I provides a low power and ultra-low cost BLE solution for wireless transmission applications.

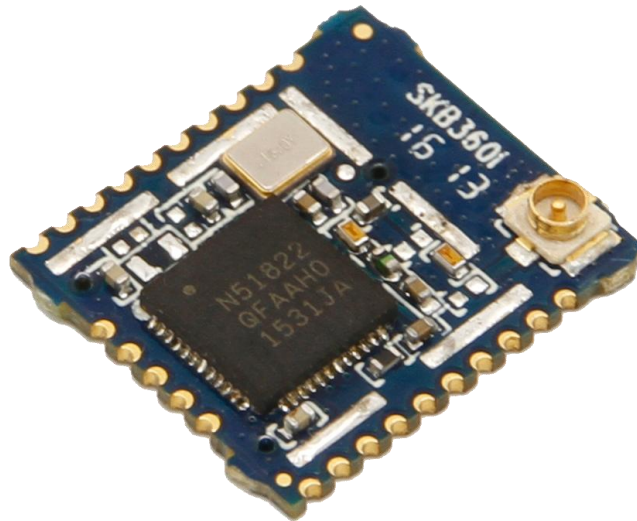


Figure 1: SKB360I Top View

## Features

- ◆ Main Chip: nRF51822
- ◆ Bluetooth® 4.0 low energy single-mode protocol stack
  - L2CAP, ATT, GAP, GATT and SM protocols
  - Central and Peripheral roles
  - GATT Client and Server
  - Full SMP support including MITM and OOB pairing
- ◆ 2.4 GHz transceiver
  - 93dBm sensitivity in Bluetooth low energy mode
  - 250Kbps, 1Mbps, 2Mbps supported data rates
  - Tx Power -20 to +4 dBm in 4 dB steps
  - Tx Power -30 dBm Whisper mode
  - RSSI (1 dB resolution)
- ◆ Flexible Power Management
  - Supply voltage range 1.8V to 3.6V
  - 4.2us wake-up using 16MHz RCOSC
  - 0.6uA at 3V OFF mode
  - 1.2uA at 3V in OFF mode +1 region RAM retention
  - 2.6uA at 3V ON mode, all blocks IDLE
- ◆ 8/9/10 bit ADC-4 configurable channels

- ◆ 20 General Purpose I/O pins
- ◆ SPI Master/Slave
- ◆ Two-wire Master (I2C compatible)
- ◆ UART (CTS/RTS)
- ◆ CPU independent Programmable Peripheral Interconnect (PPI)
- ◆ Quadrature Decoder (QDEC)
- ◆ AES HW encryption
- ◆ External antenna
- ◆ Dimension: 15.8x13.7 x2.6mm

## Applications

### ◆ Computer peripherals and I/O devices

Mouse

Keyboard

Multi-touch trackpad

### ◆ Interactive entertainment devices

Remote control

3D Glasses

Gaming controller

### ◆ Personal Area Networks

Health/fitness sensor and monitor devices

Medical devices

Key-fobs + wrist watches

### ◆ Remote control toys

## Pin Assignment

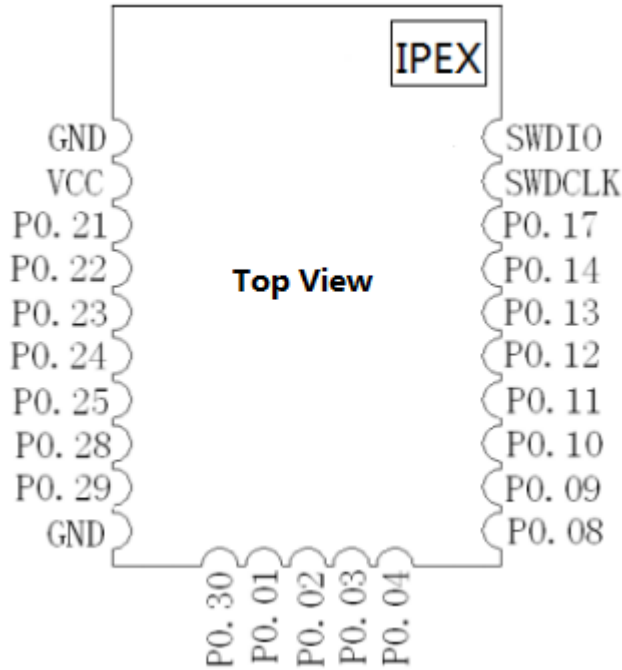


Figure 2: SKB360I Pin Assignment

## Pin Description

Pin No.	Pin name	I/O	Description	Remark
1	GND	G	Ground	
2	VCC	P	Main power Supply	1.8V to 3.6V
3	P0.21	I/O	General Purpose I/O	
4	P0.22	I/O	General Purpose I/O	
5	P0.23	I/O	General Purpose I/O	

6	P0.24	I/O	General Purpose I/O	
7	P0.25	I/O	General Purpose I/O	
8	P0.28	I/O	General Purpose I/O	
9	P0.29	I/O	General Purpose I/O	
10	GND	G	Ground	
11	P0.30	I/O	General Purpose I/O	
12	P0.01	I/O	Digital I/O; Analog input	ADC/LPCOMP input 2
13	P0.02	I/O	Digital I/O; Analog input	ADC/LPCOMP input 3
14	P0.03	I/O	Digital I/O; Analog input	ADC/LPCOMP input 4
15	P0.04	I/O	Digital I/O; Analog input	ADC/LPCOMP input 5
16	P0.08	I/O	General Purpose I/O	Default UART TX
17	P0.09	I/O	General Purpose I/O	Default UART RX
18	P0.10	I/O	General Purpose I/O	
19	P0.11	I/O	General Purpose I/O	
20	P0.12	I/O	General Purpose I/O	
21	P0.13	I/O	General Purpose I/O	
22	P0.14	I/O	General Purpose I/O	
23	P0.17	I/O	General Purpose I/O	
24	SWCLK		Hardware debug ;Flash program I/O	

25	SWDIO/ nReset	Hardware debug ;Flash program I/O; System reset (active low)	
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## Interfaces Configuration

### Power Supply

Regulated power for the SKB360I is required. The input voltage Vcc should be 1.8V to 3.6V range, current is no less than 50mA. Suitable decoupling must be provided by external decoupling circuitry (10uF and 1uF). It can reduce the Noise from power supply and increase power stability.

### Flash program I/Os

The module has two programmer pins, respectively SWCLK pin and SWDIO pin. The two pin Serial Wire Debug (SWD) interface provided as a part of the Debug Access Port (DAP) offers a flexible and powerful mechanism for non-intrusive debugging of program code. Breakpoints and single stepping are part of this support.

SWDIO can also be use as system reset pin, the system reset pin is avtive low.

### GPIO

The general purpose I/O is organized as one port with up to 20 I/Os enabling access and control of up to 20 pins through one port. Each GPIO can be accessed individually with the following user configurable features:



- Input/output direction
- Output drive strength
- Internal pull-up and pull-down resistors
- Wake-up from high or low level triggers on all pins
- Trigger interrupt on all pins
- All pins can be used by the PPI task/event system; the maximum number of pins that can be interfaced through the PPI at the same time is limited by the number of GPIOTE channels
- All pins can be individually configured to carry serial interface or quadrature demodulator signals
- All pins can be configured as PWM signal.

There are 4 ADC/LPCOMP input in the 20 I/Os.

## Serial Peripheral Interface(SPI/SPIS)

The SPI interfaces enable full duplex synchronous communication between devices. They support a three-wire (SCK, MISO, MOSI) bi-directional bus with fast data transfers. The SPI Master can communicate with multiple slaves using individual chip select signals for each of the slave devices attached to a bus. Control of chip select signals is left to the application through use of GPIO signals. SPI Master has double buffered I/O data. The SPI Slave includes EasyDMA for data transfer directly to and from RAM allowing Slave data transfers to occur while the CPU is IDLE. The SPI peripheral support SPI mode 0,1,2,and 3. The module have 3 SPI ports and they properties like following table.

Instance	Master/Slave
SPI0	Master
SPI1	Master
SPIS1	Slave

## Two-wire Interface(TWI)

The two-wire interface can communicate with a bi-directional wired-AND bus with two lines (SCL, SDA). The protocol makes it possible to interconnect up to 127 individually addressable devices. The interface is capable of clock stretching, supporting data rates of 100 kbps and 400 kbps. The module have 2 TWI ports and they properties like following table.

Instance	Master/Slave
TWI0	Master
TWI1	Master

## Universal Asynchronous Receiver/Transmitter (UART)

The Universal Asynchronous Receiver/Transmitter offers fast, full-duplex, asynchronous serial communication with built-in flow control (CTS, RTS) support in hardware up to 1 Mbps baud. Parity checking is supported.

**Notify: The GPIOs used for each SPI/TWI/UART interface line can be chosen from any GPIO on the device and are independently configurable.**

## Operating Conditions

The operating conditions are the physical parameters that the module can operate within as defined in table

Parameter	Symbol	Min.	Typ.	Max.	Units
Supply voltage, normal mode	VCC	1.8	3.0	3.6	V
Supply rise time (0V to VCC)	Tr_vcc			100	ms
Operating temperature	Ta	-25	25	75	°C

## General Purpose I/O(GPIO) specifications

Parameter	Symbol	Min.	Typ.	Max.	Units
Input high voltage	V <sub>IH</sub>	0.7VDD		VDD	V
Input low voltage	V <sub>IL</sub>	V <sub>SS</sub>		0.3VDD	V
Output high voltage	V <sub>OH</sub>	VDD-0.3		VDD	V
Output low voltage	V <sub>OL</sub>	V <sub>SS</sub>		0.3VDD	V
Pull-up resistance	R <sub>PU</sub>	11	13	16	kΩ
Pull-down resistance	P <sub>PD</sub>	11	13	16	kΩ

## Absolute Maximum Rating

Maximum ratings are the extreme limits the module can be exposed to without causing permanent damage. Exposure to absolute maximum ratings for prolonged periods of time may affect the reliability of the module.

Parameter	Symbol	Min	Max	Units
<b>Power Supply</b>				
Power Supply Volt.	VCC	-0.3	+3.9	V
<b>I/O Pin voltage</b>				
Input voltage on any input connection	$V_{IO}$	-0.3	VCC+0.3	V
Human Body Model	ESD HBM		4000	V
Charged Device Model	ESD CDM		750	V
<b>Environment</b>				
Storage Temperature	Tstg	-40	+125	°C
Flash memory Endurance	Write/erase		20000+	times
Number of times an address can be written between erase cycles			2	times

## Reference design schematic

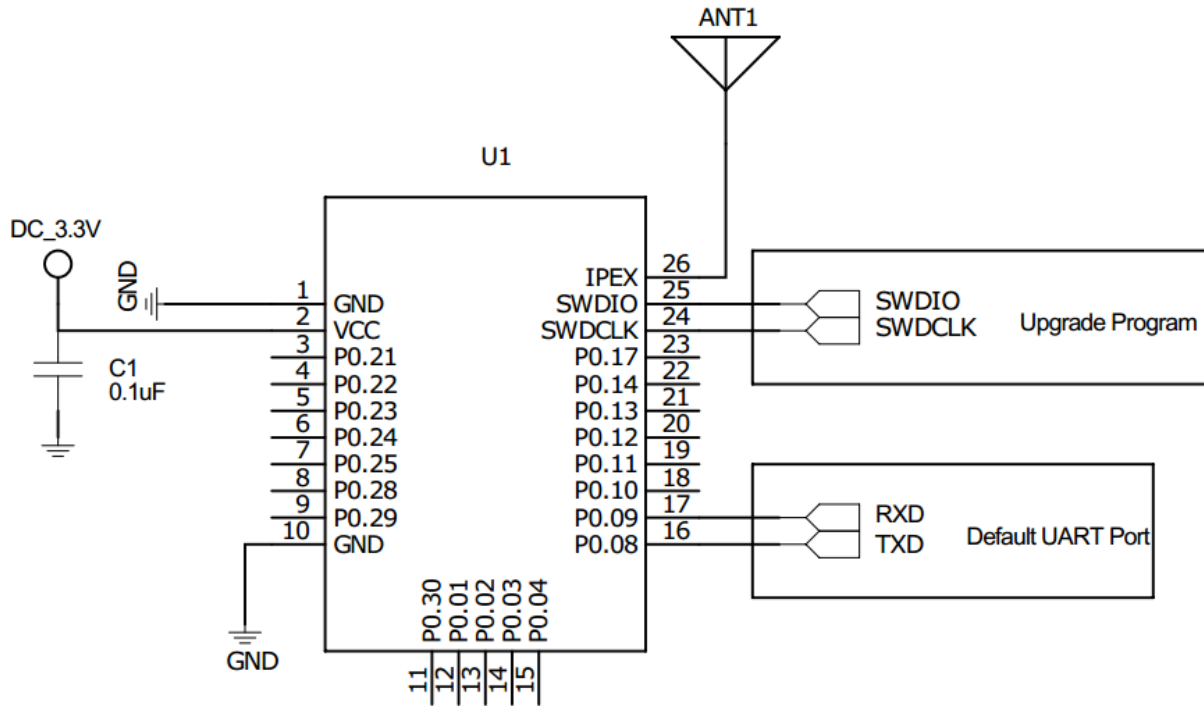


Figure 3: SKB360I schematic

## Package Outline

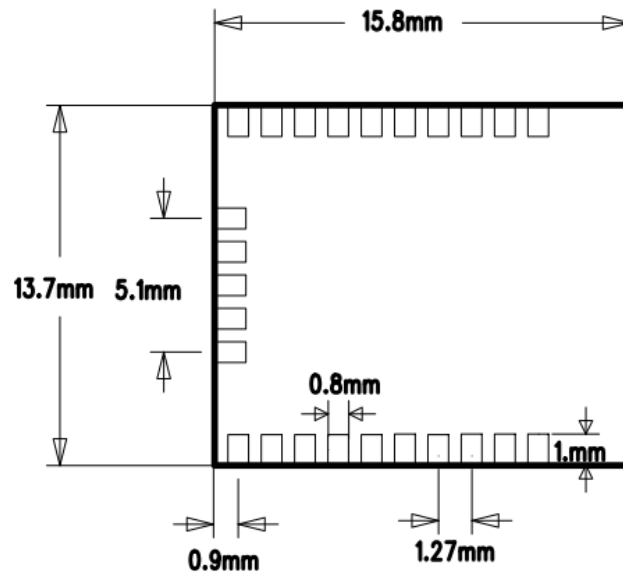


Figure 4: SKB360I Dimensions

## Recommended PCB pad pattern

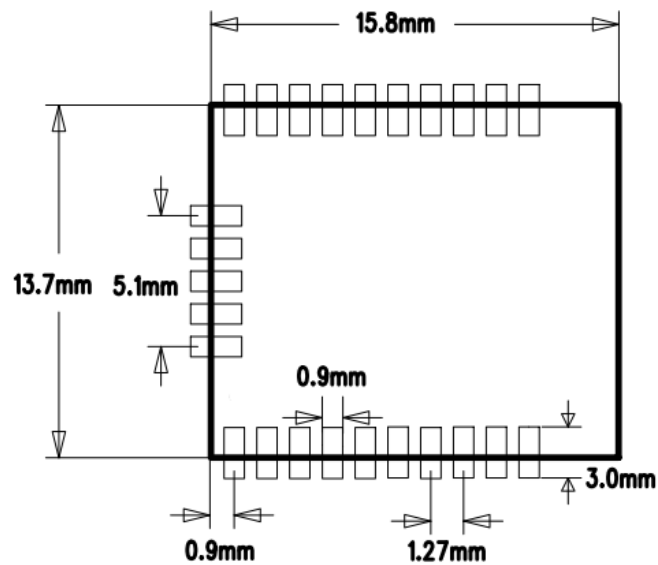


Figure 5: SKB360I Layout Package

## Manufacturing Process Recommendations

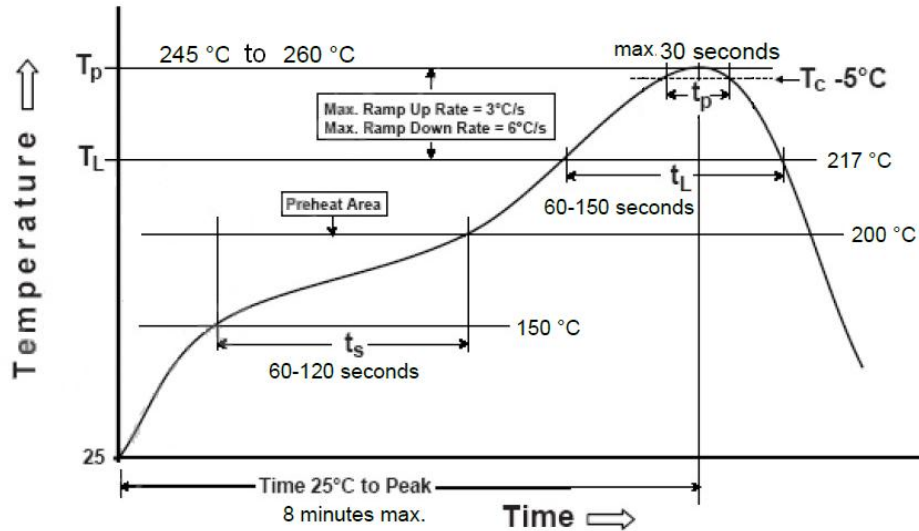


Figure 6: SKB360I Typical Leadfree Soldering Profile

**Note:** The final soldering temperature chosen at the factory depends on additional external factors like choice of soldering paste, size, thickness and properties of the baseboard, etc. Exceeding the maximum soldering temperature in the recommended soldering profile may permanently damage the module.



## Packaging Specification

SKB360I modules are shipped in reel and with 660 units per reel. Each tray is 'dry' package.

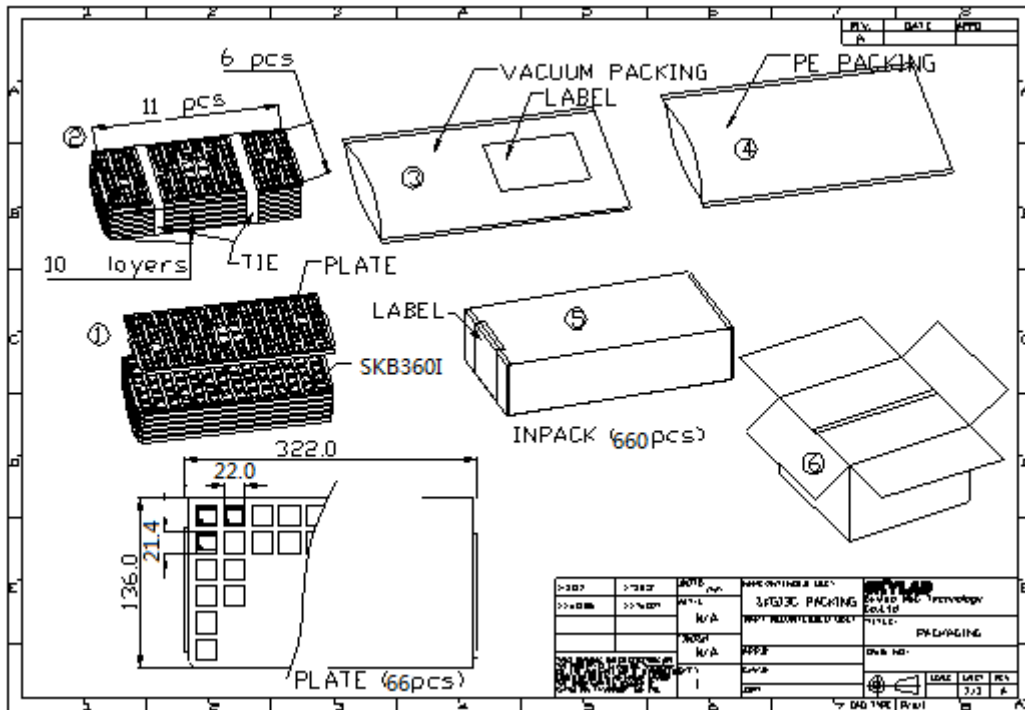


Figure 7: SKB360I Packaging

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